

STM32WB05_QFN32_2L_IPD

MB2157

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- Sheet 1: Project overview (this page)
- Sheet 2: STM32WB05 QFN32 IPD

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.

A

Notes to generate the board layout.

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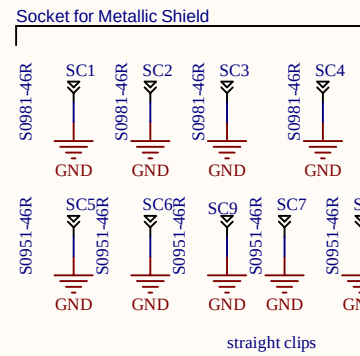
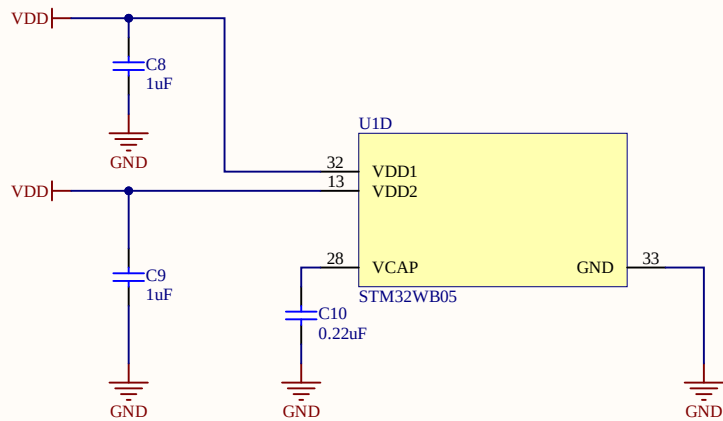
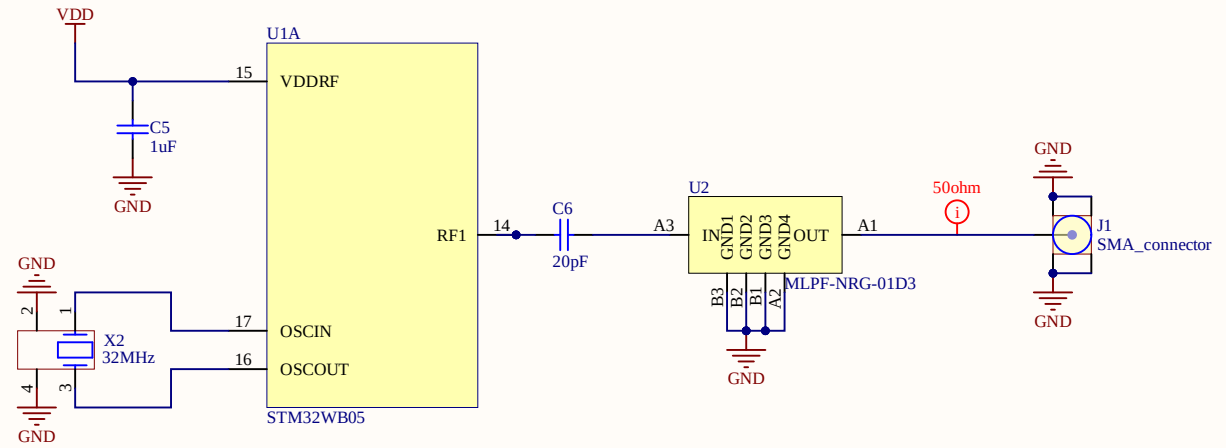
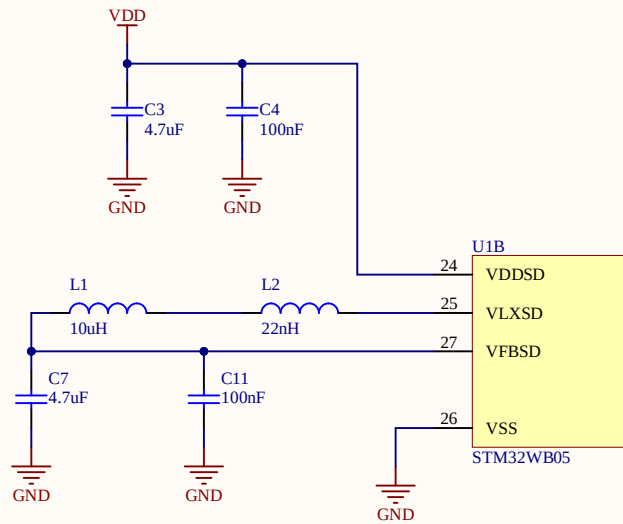
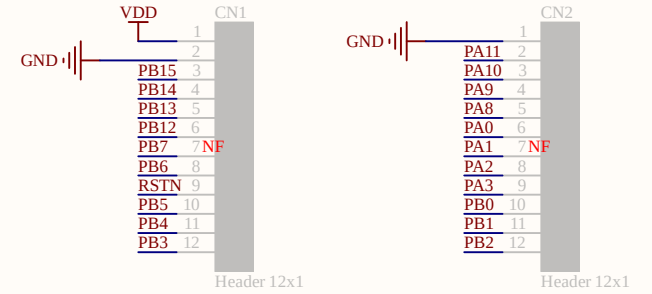
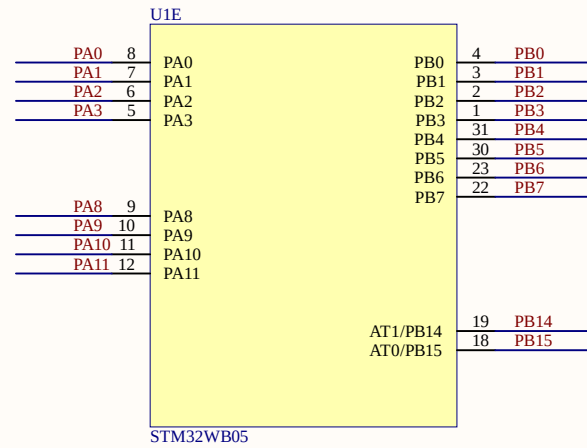
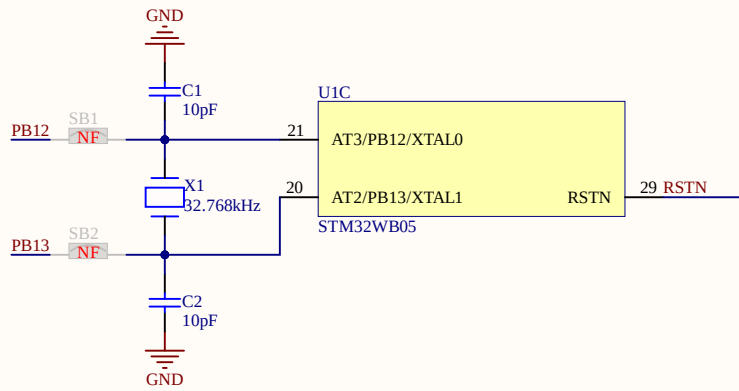
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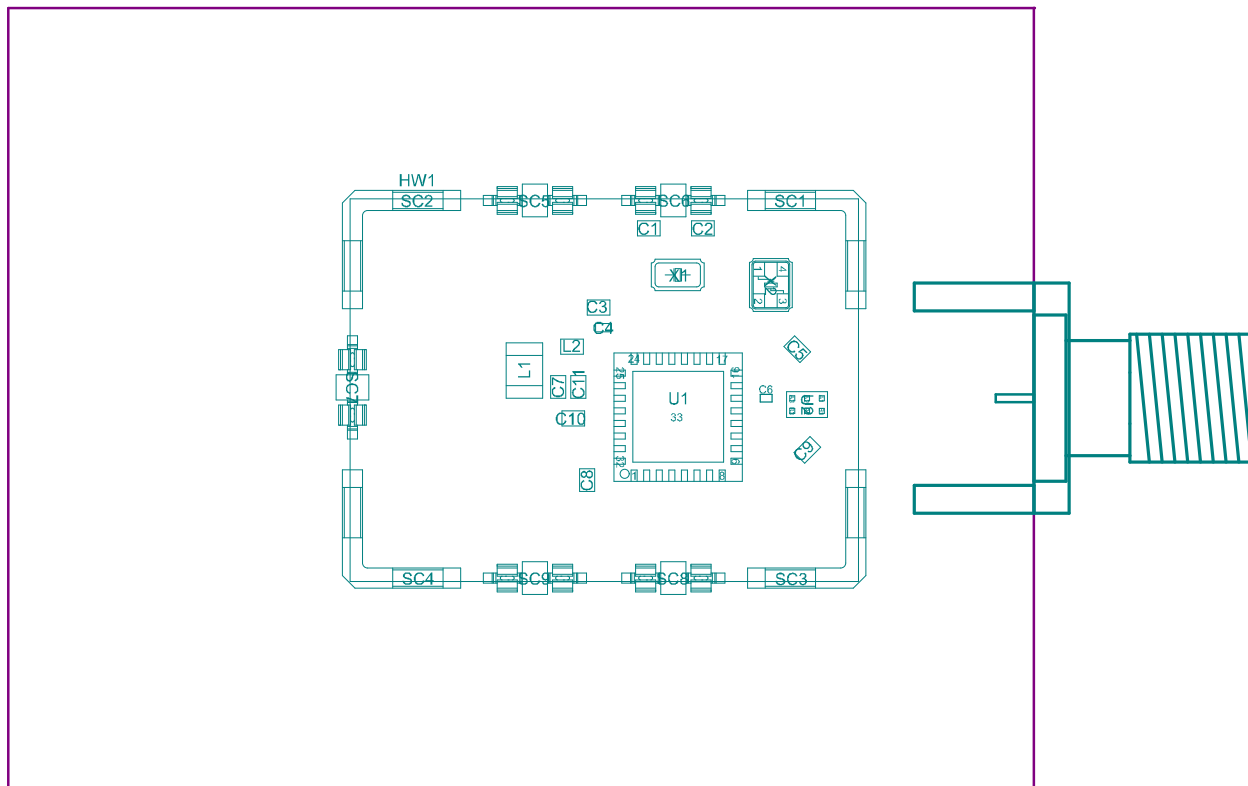
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[STM32WB05_QFN32_RefBoard_IPD_2Layers.SchDoc](#)



Title: Project overview		
Project: STM32WB05_QFN32_2L_IPD		
Variant: Variant A		
Revision: A-01		Reference: MB2157
Size: A4	Date: 07 July 2024	Sheet: 1 of 2

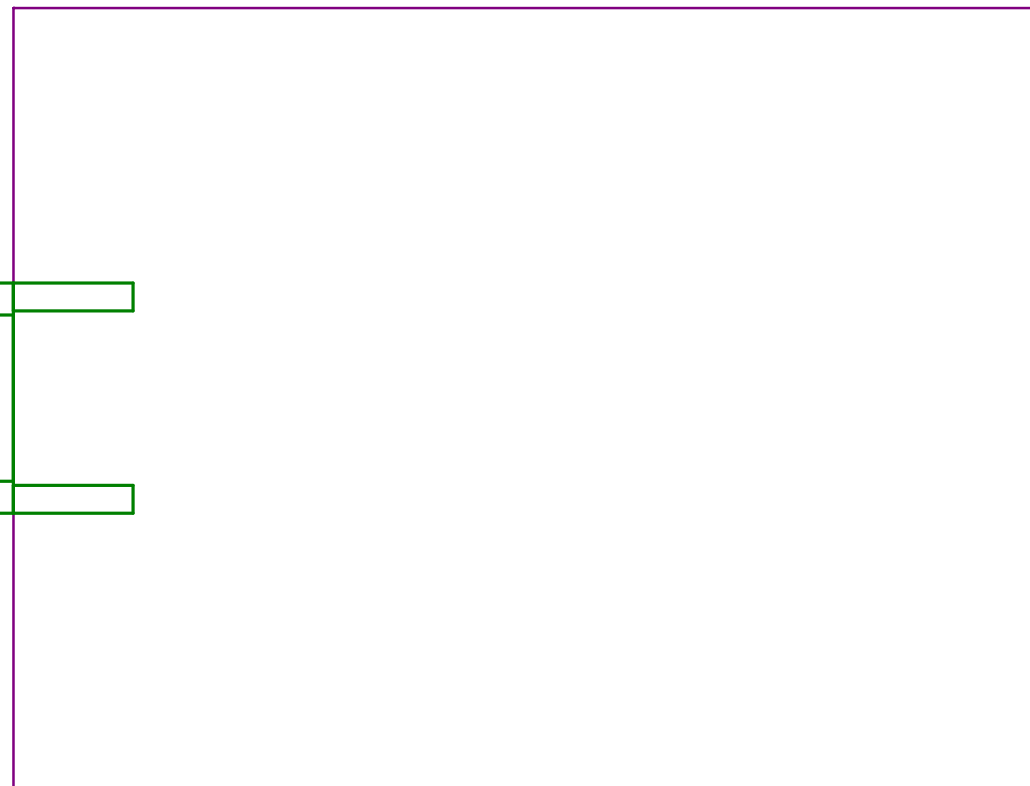
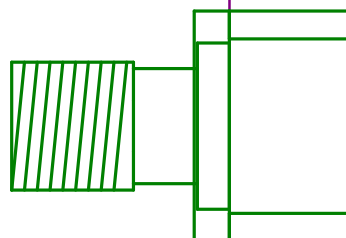






Project: STM32WB05_QFN32_2L_IPD		
Layer: Mechanical 14	Gerber: .GM14	
Variant: Variant A	Ref: MB2157	
Date: 07 July 2024	Rev: A	





Project: STM32WB05_QFN32_2L_IPD		
Layer: Mechanical 15	Gerber: .GM15	
Variant: Variant A	Ref: MB2157	
Date: 07 July 2024	Rev: A	



